

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

10-30-2003

Title of Invention

SYSTEM FOR SEARCH AND ANALYSIS OF SYSTEMATIC
DEFECTS IN INTEGRATED CIRCUITS

Application Number : 10/605,849

Confirmation Number:

First Named Applicant: Bette Bergman Reuter

Attorney Docket Number: BUR920030061US1

Art Unit: 2825

Examiner: LIN, SUN JAMES

Search string: (4855253 or 6021214 or 6140140 or 6189130 or 6285783 or 20030076989).pn

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
1	1	4855253	1989-08-08	Weber	A	438	18
2	2	6021214	2000-02-01	Evans et al.	A	382	141
3	3	6140140	2000-10-31	Hopper	A	438	8
4	4	6189130	2001-02-13	Gofman et al.	B1	716	7
5	5	6285783	2001-09-04	Isomura et al.	B1	382	147

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
1	1	20030076989	2003-04-24	Maayah et al.	A1	382	145

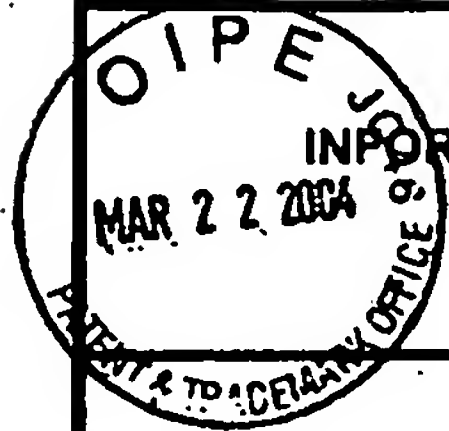
Signature

Examiner Name

Date

James Sun

3-22-07



INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

ATTY DOCKET NO.

BUR920030061US1

SERIAL NO. 10/605,849

NOT YET ASSIGNED

FILING

10/30/2003

GROUP

2825
Unknown

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
JSA	JP10301257	11/13/98	Japan				✓

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

JSA	Friedman et al., "Model-Free Estimation of Defect Clustering in Integrated Circuit Fabrication", IEEE Transactions on Semiconductor Manufacturing, Vol. 10, No. 3, August, 1997, pp. 344-359.

EXAMINER

James P. Smith

DATE CONSIDERED

3-22-07

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.